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CONTACTOR AND CHECK METHOD FOR
SEMICONDUCTOR DEVICE

Abstract

PROBLEM TO BE SOLVED: To contrive not to generate a positional displacement between a pad electrode of a semiconductor chip and a bump electrode of a contactor even in a high temperature burn-in test.

SOLUTION: A semiconductor chip 15 which is separated by a scribe line is attached at recesses 11 of a contactor 10 and a bump electrode 13 and a pad electrode of the semiconductor chip 15 are contacted and electrically connected. Side wall parts 13 between the recesses 11 of the contactor 10 are easily inserted into gap parts 16 because of the section having a trapezoidal shape, and the semiconductor chip 15 can be easily set into the recesses 11. The contactor 10 and a dicing sheet 14 having the semiconductor chip 15 are pressed to ensure electrical connections.

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